

•General Description

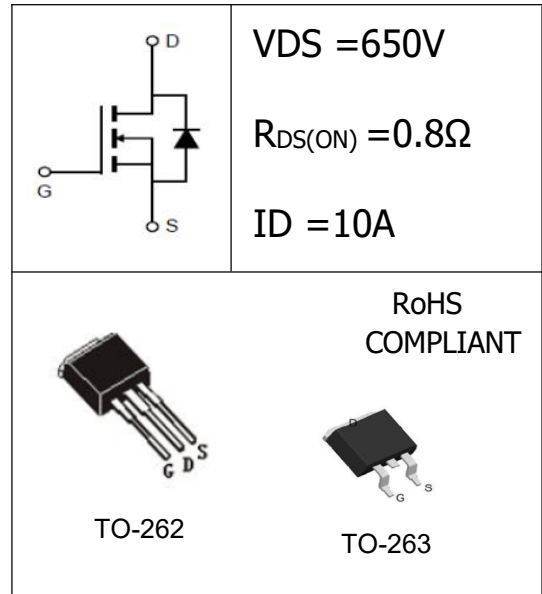
The Power MOSFET LH10N65F has the low $R_{DS(on)}$, low gate charge, fast switching and excellent avalanche characteristics. This device offers extremely fast and robust body diode, and is suitable for telecom and power supplies.

•Features

- Low Thermal Resistance
- Fast Switching
- High Input Resistance

•Application

- LED/LCD/PDP TV and monitor Lighting
- Power Supplies


•Ordering Information:

Part number	LH10N65F	LH10N65F
Package	TO-262	TO-263
Basic ordering unit (pcs)	1000	800
Normal Package Material Ordering Code	LH10N65FT62-T0262-TU	LH10N65FT63-T0263-TU
Halogen Free Ordering Code	LH10N65FT62-T0262-TU-HF	LH10N65FT63-T0263-TU-HF

•Absolute Maximum Ratings (TC = 25°C)

PARAMETER		SYMBOL	Value		UNIT
Drain-Source Breakdown Voltage		BV _{DSS}	650		V
Gate-Source Voltage		V _{GS}	±30		V
Continuous Drain Current	TC = 25°C	I _D	10		A
	TC = 100°C		6.0		
Pulsed drain current (TC = 25°C, tp limited by Tjmax) ¹		I _{DM}	38		A
Single Pulse Avalanche Energy ²		E _{AS}	230		mJ
Repetitive Avalanche Energy ¹		E _{AR}	14		mJ
Power Dissipation(TC=25°C)		P _D	TO-263: 40	TO-262: 150	W
Junction Temperature		T _J	-55~+150		°C
Storage Temperature		T _{STG}	-55~+150		°C

●Electronic Characteristics

PARAMETER	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	650	--	--	V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2.0	--	4.0	V
Drain-source On Resistance ³	$R_{DS(ON)}$	$V_{GS}=10V, I_D=4A$	--	0.8	1.0	Ω
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=650V, V_{GS}=0V, T_J=25^\circ C$	--	--	1	μA
		$V_{DS}=480V, V_{GS}=0V, T_J=125^\circ C$	--	--	100	
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 30$	--	--	± 100	nA
Forward Transconductance ³	g_{fs}	$V_{DS}=15V, I_D=4A$	--	3	--	S
Input Capacitance	C_{iss}	$V_{GS}=0V,$ $V_{DS}=25V$ $f=1.0MHz$	--	1450	--	pF
Output Capacitance	C_{oss}		--	108	--	
Reverse transfer Capacitance	C_{rss}		--	19	--	
Turn-Off Delay Time ³	$T_d(off)$	$V_{DD}=300V, I_D=8A$ $R_G=25\Omega$	--	81	--	ns
Total Gate Charge ³	Q_g	$I_D=8A,$ $V_{DS}=520V$ $V_{GS}=10V$	--	31.6	60	nC
Gate-to-Source Charge ³	Q_{gs}		--	7.4	15	
Gate-to-Drain Charge ³	Q_{gd}		--	11	20	
Continuous Diode Forward Current	I_S		--	--	8	A
Pulsed Diode Forward Current	I_{SM}		--	--	32	A
Diode Forward Voltage	V_{SD}	$T_J=25^\circ C, I_S=8A$ $V_{GS}=0V$	--	--	1.4	V
Reverse Recovery Time ³	t_{rr}	$I_f=I_S$ $di_F/dt=100A/\mu s$	--	365	--	ns
Reverse Recovery Charge ³	Q_{rr}		--	3.4	--	μC

●Thermal Characteristics

PARAMETER	SYMBOL	MAX		UNIT
		TO-220F	TO-220	
Thermal Resistance Junction-case	R_{thJC}	3.13	0.9	$^\circ C/W$
Thermal Resistance Junction-ambient	R_{thJA}	62.5	62.5	$^\circ C/W$

Notes:

1.Repetitive Rating: Pulse width limited by maximum junction temperature.

2. $I_{AS}=8A, V_{DD}=50V, R_G=25\Omega, L=10Mh$, Starting $T_J=25^\circ C$

3. Pulse Test : Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$

• **Typical Characteristics**

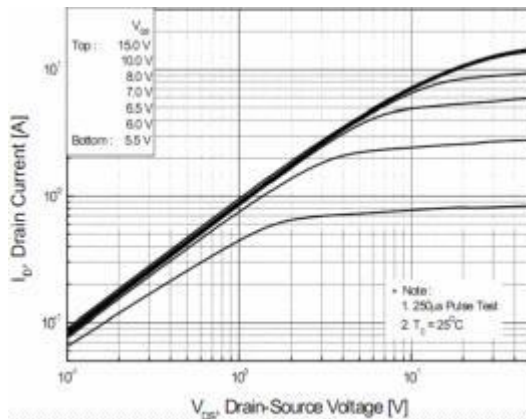


Fig1 Typical Output Characteristics, Tc=25°C

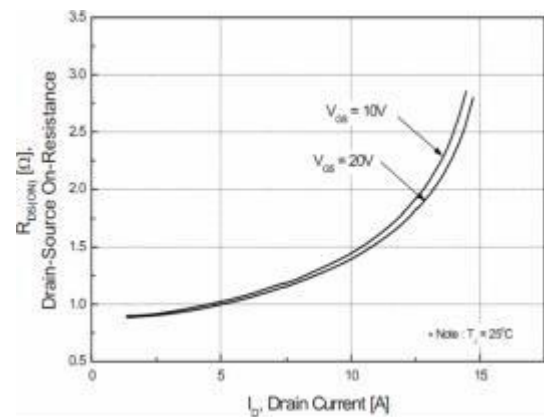


Fig2 On-Resistance Vs. Drain Current and Gate Voltage

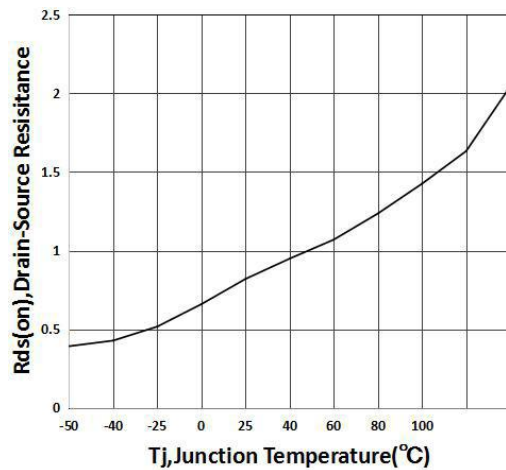


Fig3 Normalized On-Resistance Vs. Temperature

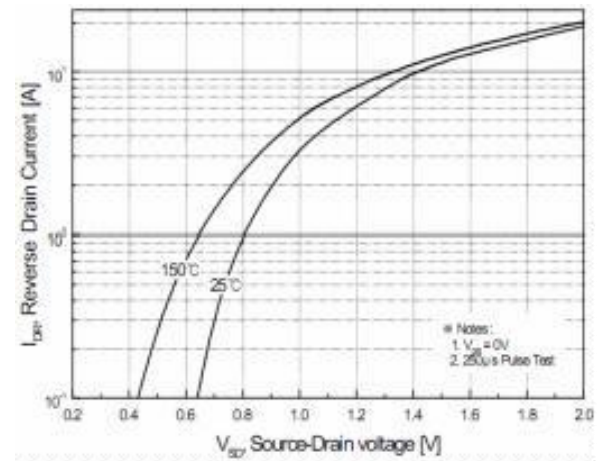


Fig4 Typical Source-Drain Diode Forward Voltage

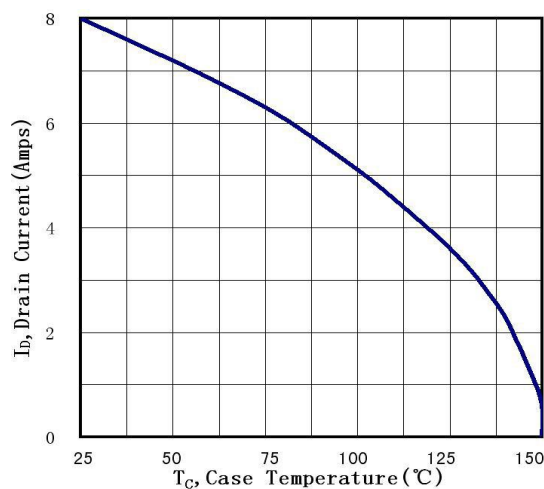


Fig5 Maximum Drain Current Vs. Case Temperature

● **Typical Characteristics**(cont.)

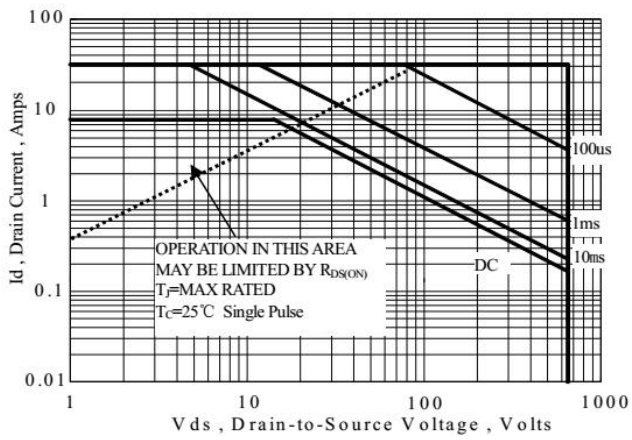


Fig6 Maximum Safe Operating Area (TO-262)

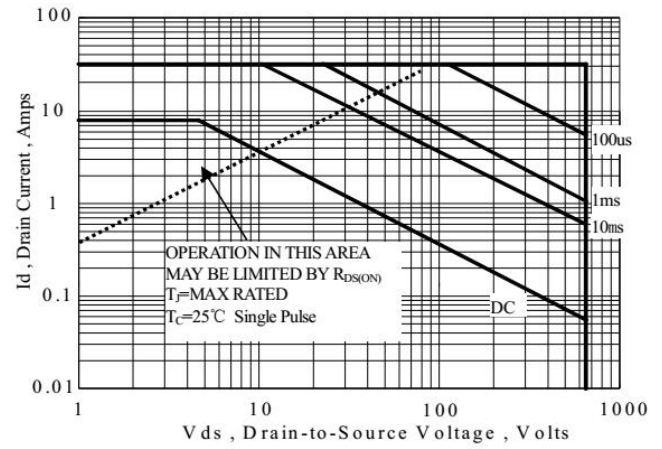


Fig7 Maximum Safe Operating Area (TO-263)